DATA BOOK
PACKAGE OUTLINE

LEADFRAME EXAMPLE
4218277

DRAFTER:	T. LEQUANG	DATE:	07/30/2015
DESIGNER:		DATE:	
CHECKER:	ANIS FAUZI	DATE:	12/26/2023
ENGINEER:	EUGENE LEE	DATE:	12/26/2023
APPROVED:	K. SINCERBOX & D. CHIN	DATE:	12/26/2023
RELEASED:	NAZRIN CHU	DATE:	12/26/2023
TEMPLATE INFO:	EDGE# 4218519	DATE:	03/20/2013

DIMENSIONS IN MILLIMETERS

TEXAS INSTRUMENTS
SEMICONDUCTOR OPERATIONS

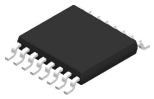
CODE IDENTITY NUMBER 01295

ePOD, PWP0016G / TSSOP,
16 PIN, 0.65 MM PITCH

SCALE	SIZE		REV	PAGE
8X	A	4218975	C	1 OF 5

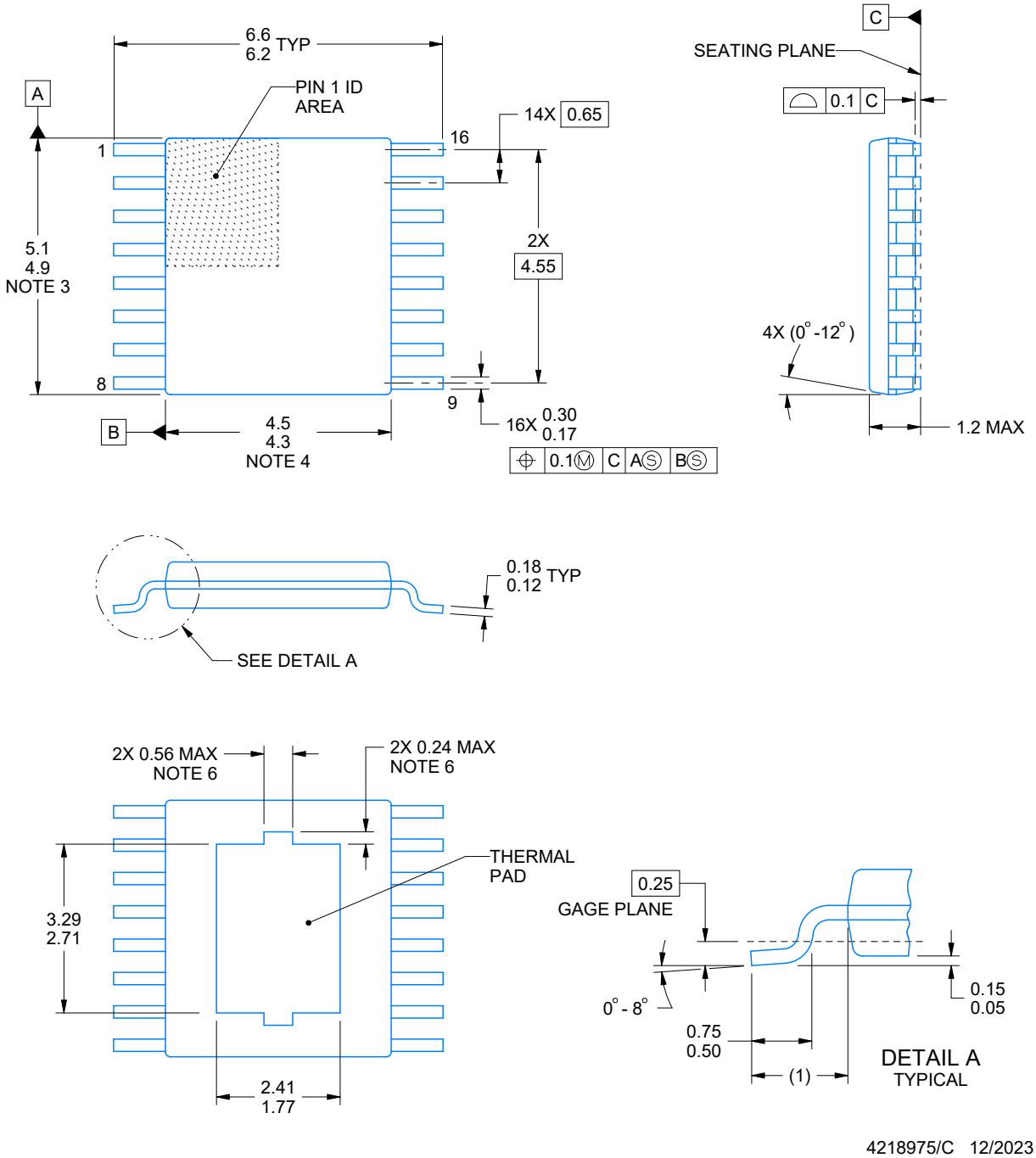
PACKAGE OUTLINE

PWP0016G



PowerPAD™ TSSOP - 1.2 mm max height

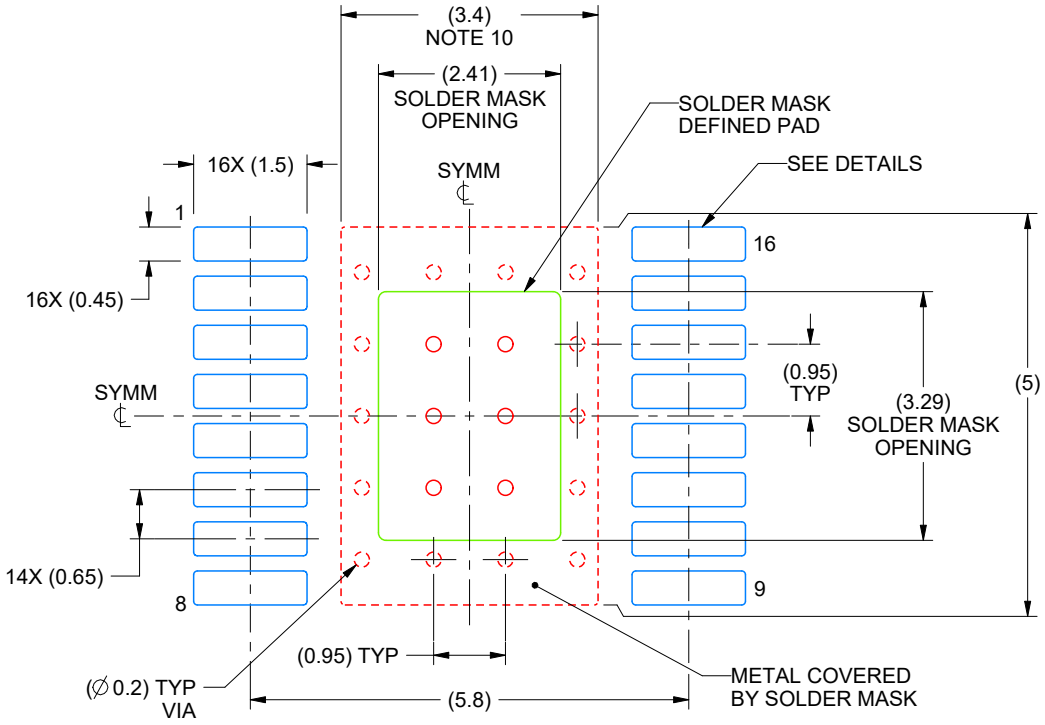
PLASTIC SMALL OUTLINE



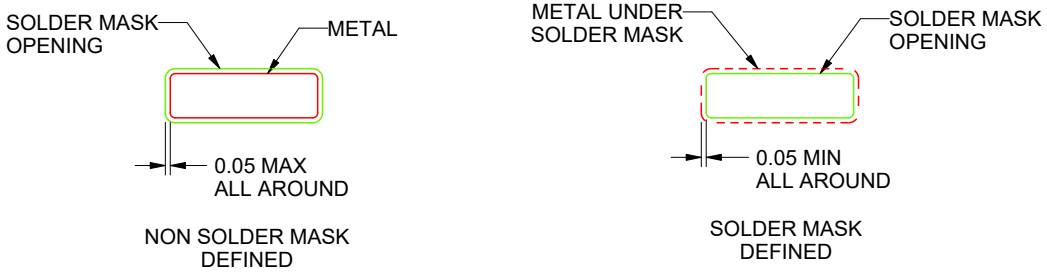
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.
6. Features may not present.



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
PADS 1-16

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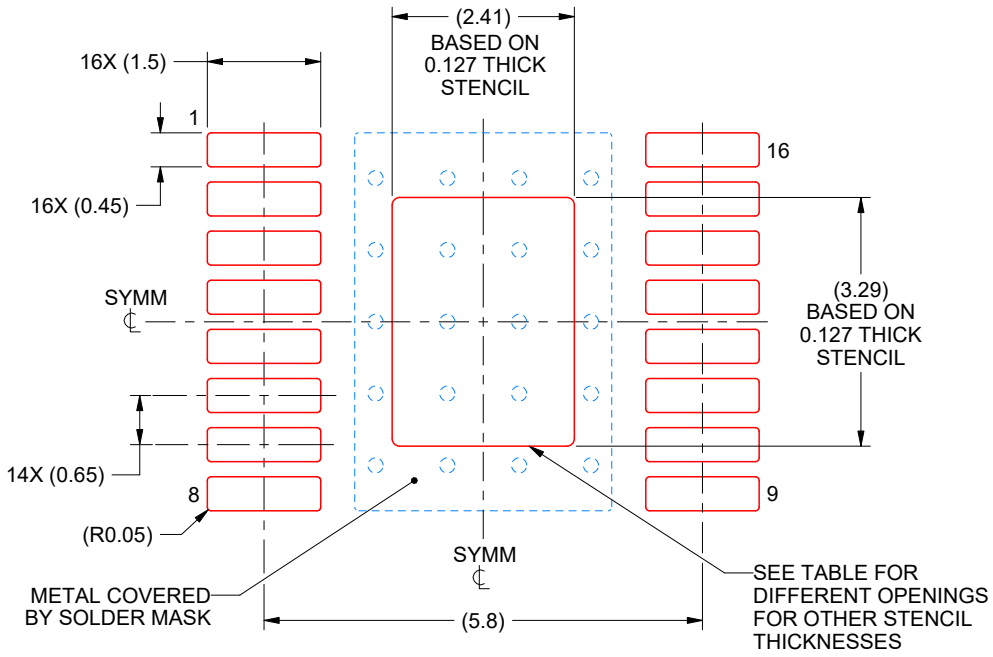
NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
9. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
10. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:10X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	2.69 X 3.68
0.127	2.41 X 3.29 (SHOWN)
0.152	2.20 X 3.00
0.178	2.04 X 2.78

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2151855	07/30/2015	J. HOLLOWAY / T. LEQUANG
B	CORRECT EDGE DESCRIPTION; ADD TSSOP TO TITLE AND SHEET HEADERS. CORRECT SOLDER STENCIL OPENING TABLE.	2155159	01/25/2016	E.REY / K.SINCERBOX
C	UPDATE LEAD WIDTH SPEC & BODY DRAFT ANGLE	2206758	12/26/2023	EUGENE LEE / NAZRIN CHU